

25. (temporarily removed from consideration) (Amended once) The method of claim 19 wherein coupling at least one semiconductor die comprises coupling memory chips to the interposer.

26. (Amended once) The method of claim 19, further comprising: creating a plurality of contacts on the [first surface] substrate; and electrically connecting said selected ones of the plurality of conductive pads to the plurality of contacts.

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#### REMARKS

Claims 22, 24 and 25 are not canceled, but have been withdrawn from consideration at this time, pending determination of allowability of the generic claims.

Claims 19-21, 23 and 26 have been rejected under 35 USC 103(a) as being unpatentable over U.S. patent 5,483,421 ("Gedney"). Applicants respectfully traverse this rejection in view of the amended claims.

Independent claim 19 recites testing the semiconductor die and coupling the interposer to a substrate if the test passes. Gedney does not disclose or suggest an assembly process that is conditionally dependent on a successful intermediate test result in this manner. Claim 20 provides further limitations by reciting that the test is run at integrated cache speeds. Claim 23 provides additional limitations by reciting that the interposer is not coupled to the substrate if the test does not pass. Gedney does not disclose or suggest these limitations, either.

As stated in the written description, the conventional procedure is to completely assemble before testing, making any rework or scrap operation more expensive because the full assembly is at risk of being repaired or discarded, rather than interrupting the assembly procedure before this stage is reached if the testing fails. The written description further states that the conventional full assembly must be tested at speeds less

than the integrated circuit is capable of. Thus, the recited limitations are not obvious, as they are contrary to conventional procedures in this field.

#### CONCLUSION

For the aforementioned reasons, Applicants maintain that claims 19-21, 23 and 26 are now in condition for allowance. Applicants further maintain that since generic claim 19 is in condition for allowance, claims 22, 24 and 25 should now be considered by the Examiner and found allowable as well. A finding of allowance by the Examiner on claims 19-26 is therefore respectfully requested. No fee is believed due with this response. In this is incorrect, please charge any insufficiency or credit any overpayment to Deposit Account No. 02-2666.

Respectfully submitted,

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